



Material Content Data Sheet



Sales Product Name		TLE9260QX		Issued		25. January 2018		
MA#		MA001660470						
Package		PG-VQFN-48-31		Weight*		129.39 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.471	1.91	1.91	19100	19100
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		138	
	non noble metal	zinc	7440-66-6	0.072	0.06		554	
	non noble metal	iron	7439-89-6	1.433	1.11		11076	
wire	non noble metal	copper	7440-50-8	58.193	44.97	46.15	449750	461518
	non noble metal	copper	7440-50-8	0.552	0.43	0.43	4263	4263
	encapsulation	organic material	carbon black	1333-86-4	0.188	0.15		1453
	plastics	epoxy resin	-	7.958	6.15		61505	
		inorganic material	silicondioxide	60676-86-0	54.516	42.13	48.43	421332
leadfinish	non noble metal	tin	7440-31-5	2.596	2.01	2.01	20066	20066
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4744	4744
glue	plastics	epoxy resin	-	0.179	0.14		1384	
		noble metal	silver	7440-22-4	0.600	0.46	0.60	4635
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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